SDFS013A - MARCH 1987 - REVISED OCTOBER 1993

 Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

These devices contain four independent 2-input NAND buffer gates with open-collector outputs. They perform the Boolean functions $Y = \overline{A} \bullet \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

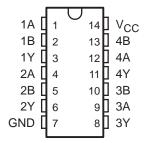
The open-collector outputs require pullup resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher V_{OH} levels.

The SN54F38 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74F38 is characterized for operation from 0°C to 70°C.

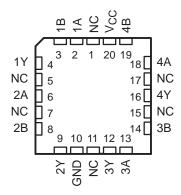
FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Н	L
L	Χ	Н
X	L	Н

SN54F38...J PACKAGE SN74F38...D OR N PACKAGE (TOP VIEW)

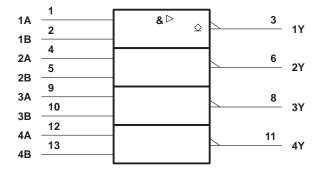


SN54F38 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

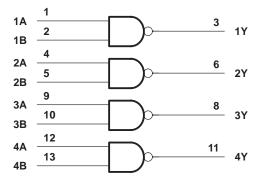
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)





SN54F38, SN74F38 QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Input current range	30 mA to 5 mA
Voltage range applied to any output in the high state	0.5 V to V _{CC}
Current into any output in the low state	128 mA
Operating free-air temperature range: SN54F38	–55°C to 125°C
SN74F38	0°C to 70°C
Storage temperature range	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		5	N54F38		SN74F38			LINUT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
liK	Input clamp current			-18			-18	mA
Vон	High-level output voltage			4.5			4.5	V
lOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	$\begin{array}{cccccccccccccccccccccccccccccccccccc$,	SN54F38		5	UNIT			
PARAMETER		TEST CONDITIONS	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$		-0.73	-1.2			-1.2	V
V	$V_{CC} = 4.5 \text{ V},$	I _{OL} = 48 mA		0.3	0.5		0.3	0.5	V
VOL	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 64 \text{ mA}$		0.3	0.5		0.3	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
lіН	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			- 0.6			- 0.6	mA
loн	V _{CC} = 4.5 V				250			250	μΑ
Іссн	$V_{CC} = 5.5 \text{ V},$	V _I = 0		4	7		4	7	mA
ICCL	$V_{CC} = 5.5 \text{ V},$	V _I = 4.5 V		22	30		22	30	mA

 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

SN54F38, SN74F38 QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS SDFS013A - MARCH 1987 - REVISED OCTOBER 1993

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _I R _I	$V_{CC} = 5 \text{ V},$ $C_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = 25^{\circ}\text{C}$			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω, T_A = MIN to MAX [†] SN54F38 SN74F38			
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	6.7	9.6	12.5	6.2	14	6.7	13	ns
^t PHL	AUID		1	2.6	5	1	6.5	1	5.5	110

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74F38D	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	0 to 70	F38
SN74F38DR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F38
SN74F38DR.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F38
SN74F38DRG4	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F38
SN74F38N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F38N
SN74F38N.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F38N
SN74F38N.B	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F38N
SN74F38NSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F38
SN74F38NSR.A	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F38
SN74F38NSR.B	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F38

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F38DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74F38NSR	SOP	NS	14	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1

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*All dimensions are nominal

Device	Package Type Package Drawing F		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F38DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74F38NSR	SOP	NS	14	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

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TUBE

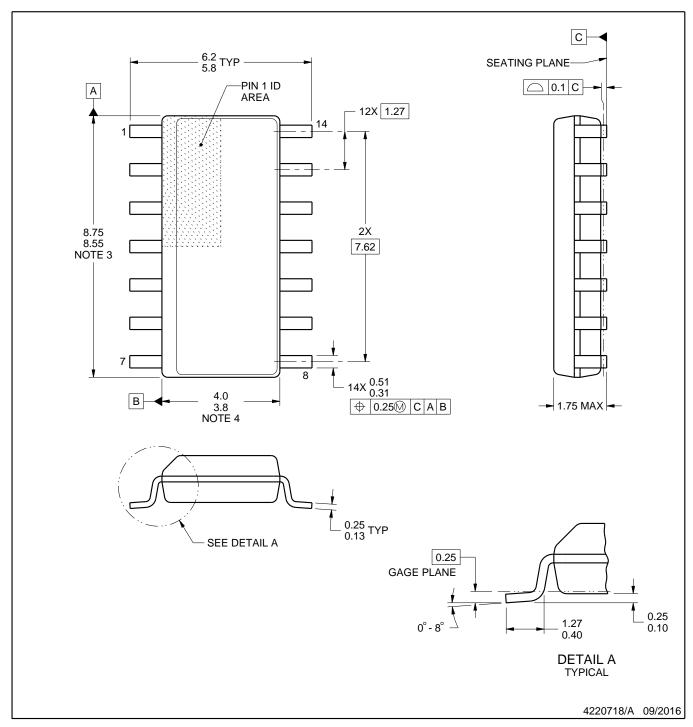


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74F38N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F38N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F38N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74F38N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74F38N.B	N	PDIP	14	25	506	13.97	11230	4.32
SN74F38N.B	N	PDIP	14	25	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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